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Directly mates with a comapatoble SMT adapter.

Minimum real estate required

Compression plate distributes evenly

Clamshell lid

Materials:

Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.



Socket Base: Black anodized Aluminum. Height = 6 mm.



Compression Plate: Black anodized Aluminum. Thickness = 12 mm.



Compression Screw: Clear anodized Aluminum. Height = 27 mm, Fluted Knob





Stamped Contact: BeCu, Au Plate Spring SS, Au Plate



Pogo Pin Guides: Peek



Pogo Pin Guide Screw: Pan head phillips, 18-8



0-80 thread, 3/16" long.



Latch: Black anodized Aluminum.

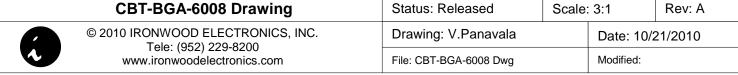


Substrate: 3.18mm ±0.125mm [0.125" ±0.005"] FR4/G10 or equivalent high temp material. Non-clad.



Pin: Brass - PS-2 Plating: 10u" Au over 50u" Ni min.

Rev: A



Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

Compatible BGA Spec

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Ø0.25 Z X Y

Ø0.10

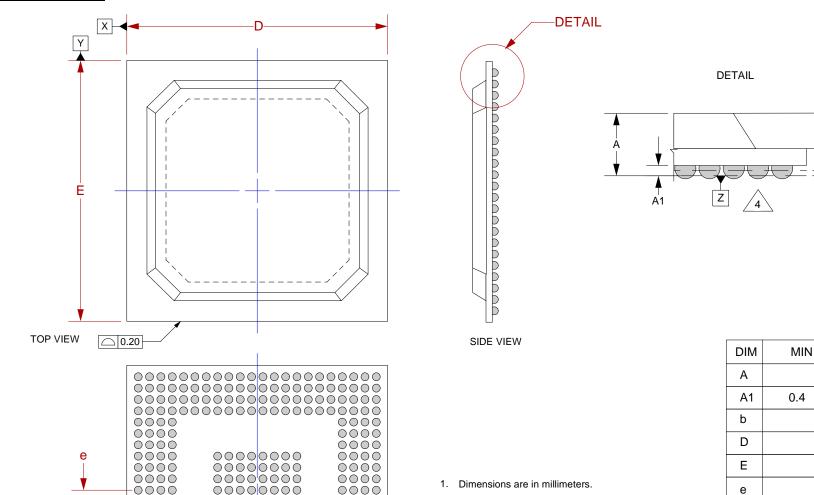
BOTTOM VIEW

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23.00 BSC

23.00 BSC

1.0 BSC

0.25 Z

MAX 2.45

0.6

0.70

 Interpret dimensions and tolerances per ASME Y14.5M-1994.

Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.

Datum Z (seating plane) is defined by the spherical crowns of the solder balls.

Parallelism measurement shall exclude any effect of mark on top surface of package.

CBT-BGA-6008 Drawing		Status: Released	Scale: 3:1		Rev: A
© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: V.Panavala		Date: 10/21/2010		
		File: CBT-BGA-6008 Dwg		Modified:	

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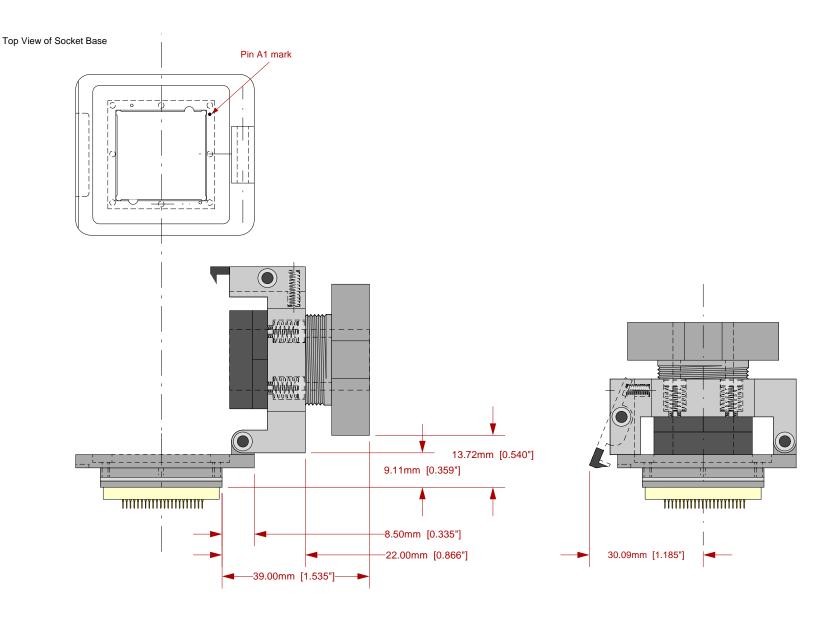
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CBT-BGA-6008 Drawing		Status: Released	Scale: 1:1		Rev: A
© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: V.Panavala		Date: 10/21/2010		
		File: CBT-BGA-6008 Dwg		Modified:	

All dimensions are in mm.
All tolerences are +/- 0.125mm.
(Unless stated otherwise)